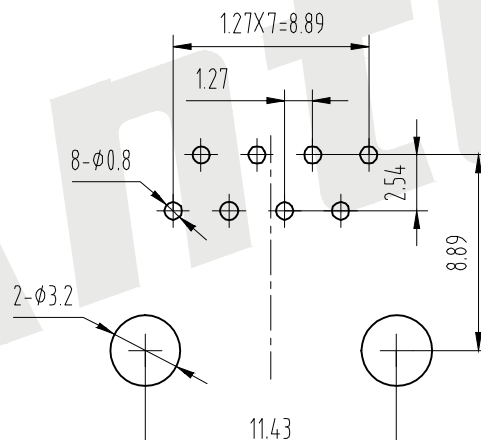
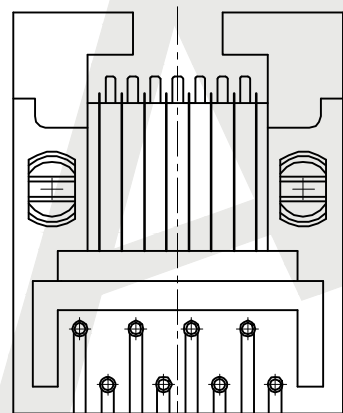
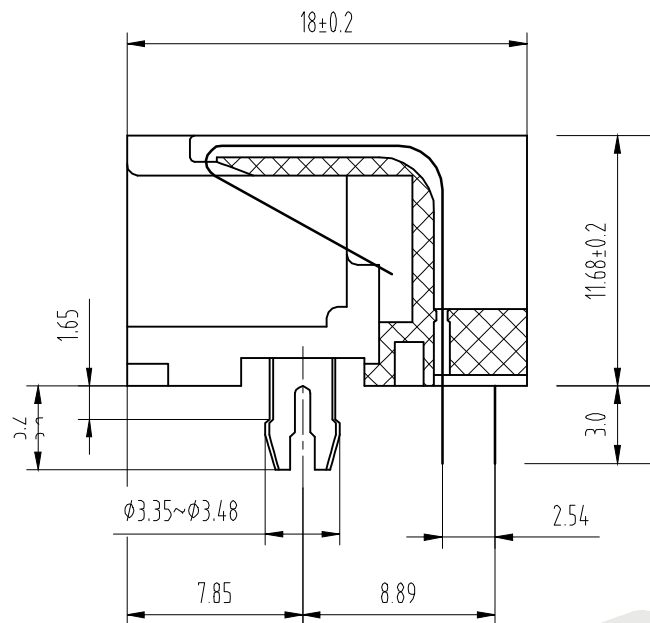
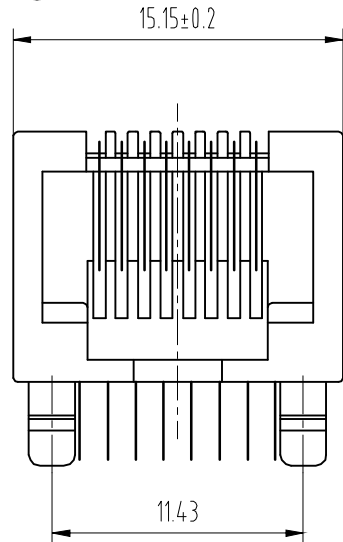


HSF

RoHS



PC Board Layout
Component Side Shown

NOTES:
MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
 2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
 3. PLATING: SELECTING GOLD PLATING $1\mu\sim50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
 4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
 2. CURRENT RATING: 1.5AMP
 3. CONTACT RESISTANCE: 30MILLIOHMS MAX
 4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
 5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIROMENTAL

1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

ATRJ5321 - $\frac{8P}{1}$ - $\frac{8C}{2}$ - $\frac{X}{3}$ - $\frac{A}{4}$ - $\frac{A}{5}$

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating
G0: Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3: 10U" Gold
G4: 15U" Gold
G5: 30U" Gold
SN: Tin

- ⑤ Shield
A: W/O Shield
B: Half Shield
C: Shield W/Eml
D: Shield W/O Eml

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

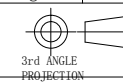
Antenk® ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 05/09/2019
CHECK BobYang DATE 05/09/2019

TITLE: RJ11 Jack 8P8C, Side entry, 1X1Port, Full plastic

DRAWING NO: ATRJ5321-8P8C-X-A

PRODUCT NO: ATRJ5321-8P8C-X-A



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		
6		
7		
8		